# MOTH-EYE ANTIREFLECTION FOR SMALL SATELLITES

# SMALL SAT CONFERENCE 08/11/15 HUGH PODMORE REGINA LEE

creative	passionate	rational	confident	ingenious

# OUTLINE

- Introduction to Moth-Eye Antireflection (MEAR)
- Design and Fabrication of MEAR surfaces for CubeSats
- Characterization of MEAR surface and implications for CubeSats
- Conclusions, contributions and future work



# **MEAR FOR CUBESATS**

- High-quality science requires large power budgets.
- CubeSat volume constrains power:
  - Small surface area for light collection
  - Adding arrays possible, but difficult
  - Small surface, high incidence
- Many CubeSats adhere their own coverglass. Can this glass be improved to increase transmission at high angles of incidence?





CAD model of 3-U SIGMA CubeSat operated by Kyung-Hee University

# **MEAR THEORY**



- Components 180° out of phase
- Interference reduces
   impedance
- Infinite boundaries →
   Infinite reflections
- Infinite reflections → Total destructive interference



#### **MEAR THEORY**





# **MEAR THEORY**

- Nanostructured surfaces reduce reflection by subwavelength antireflection (MEAR-effect)
- MEAR conditions:
  - Maximum pitch:  $\Lambda < \lambda_{min}/2n$
  - Minimum height:  $h > 0.4 \lambda_{max}$
- Profile is important: index changes as a function of the fill factor.
  - "Klopfenstein tapers" (5-th order poly, sine curve) are ideal but not necessary provided index is graded
- MEAR surfaces provide strong antireflection
   even at high incidence



## **MOTH EYE DESIGN**



- Simulate transmission using Rigorous Coupled Wave Analysis (RCWA)
  - GD-CALC, MPB, S<sup>4</sup>
- Determine transmittance
- Convolve with EQE & Spectra, integrate across wavelength to get P(θ)
- Comparison with attitude data yields power production



# **MOTH EYE DESIGN**



- Simulate transmission using Rigorous Coupled Wave Analysis (RCWA)
  - GD-CALC, MPB, S<sup>4</sup>
  - Determine transmittance
  - Convolve with EQE & Spectra, integrate across wavelength to get P(θ)
- Comparison with attitude data yields power production



# **MOTH EYE FABRICATION OBJECTIVES**

- Feature height,
  - EMT-TMM suggests diminishing returns at h > 500nm
  - RCWA optimization gives h = 1204nm
- Spacing  $\Lambda < 150$  nm
- Pyramidal or 5<sup>th</sup> order polynomial profile

# REALITY

- Feature height, spacing and profile highly dependent on fabrication process
- "You can't coat a CubeSat in gold."



# **MOTH EYE FABRICATION**



- Nanosphere Lithography (NSL)
- Assembly of etch mask by colloidal self-assembly
- RIE in CHF3/SF6 Plasma
- Etch mask made of PS
   Nanospheres
- Cheap & Simple, produces aspect ratio 5:1



# NANOSPHERE LITHOGRAPHY



- Produces monolayer in hexagonally close packed (HCP) configuration.
- Defects at small scale
   due to particle size.





#### **SIZE REDUCTION**



#### **RIE ETCHING**



 Previously obtained well-ordered structures, unable to achieve high aspect ratios







- More recently obtained higher aspect ratio structures.
- Structures ordered with inter-particle columns



#### **RIE ETCHING**



- Inter-particle structures the result of micromasking
- "RIE-Grass" or Glass grass
- MEAR structures with no mask?





#### **RIE ETCHING**



- 1177nm height Spacing 130nm
  - Tube-like appearance consistent with literature
- Do these structures exhibit MEAR?







- Left NSL Fabrication
- Right Maskless, single step fabrication





- A) Solar cell panel on rotator& translators.
- B) Beam power sensor
- C) Alignment laser
- D) Imaging screen

G) Shutter

E) 75W Xenon arc lamp

F) 33mm diameter collimator

SCHOOL OF ENGINEERING

UNIVERSI

UNIVERSIT









 350nm MEAR shows poor improvement, esp. at high incidence, poor AR in infrared due to low height





 1177nm MEAR shows significant improvement at high incidence, well beyond commercial ARC





Time (Months)

Orbit	Mean	Maximum	Minimum
A-Train	4.9%	5.0%	4.7%
Iridium	4.5%	6.0%	3.7%
ISS	4.6%	5.9%	3.7%
A-Train (MgF <sub>2</sub> )	1.2%	1.2%	1.2%
Iridium (MgF <sub>2</sub> )	1.2%	1.3%	1.2%
ISS (MgF <sub>2</sub> )	1.2%	1.3%	1.2%





Orbit	Mean	Maximum	Minimum
A-Train	7.0%	7.6%	6.4%
Iridium	5.5%	9.4%	3.7%
ISS	6.5%	11.7%	3.7%
A-Train (MgF <sub>2</sub> )	1.3%	1.3%	1.2%
Iridium (MgF <sub>2</sub> )	1.2%	1.4%	1.2%
ISS (MgF <sub>2</sub> )	1.3%	1.5%	1.2%





Equivalent to an extra 3.5-4.0W h / day Effect is enhanced during lowillumination



#### RESULTS

Orbit	Mean	Maximum	Minimum	
1177nm MEAR Surfaces				
A-Train	4.9%	5.0%	4.7%	
Iridium	4.5%	6.0%	3.7%	
ISS	4.6%	5.9%	3.7%	
A-Train - DART	7.0%	7.6%	6.4%	
Iridium - DART	5.5%	9.4%	3.7%	
ISS - DART	6.5%	11.7%	3.7%	
MgF <sub>2</sub> AR Coatings				
A-Train	1.2%	1.2%	1.2%	
Iridium	1.2%	1.3%	1.2%	
ISS	1.2%	1.3%	1.2%	
A-Train – DART	1.3%	1.3%	1.2%	
Iridium – DART	1.2%	1.4%	1.2%	
ISS – DART	1.3%	1.5%	1.2%	

• 3.5-4.0W h / day

- Effect enhanced during low light
- MEAR surfaces realized in single step fabrication





## **SUMMARY & CONCLUSIONS**

- MEAR Surfaces for CubeSats designed using RCWA.
  - Ideal height found to be 1204.1nm, pitch <150nm
- MEAR Surfaces fabricated by NSL and single-step "grass growth"
- MEAR Surfaces characterized in solar simulation environment
- Average expected power increase on orbit 4.7% for Nadir pointing, 6.3% for Dart.
  - Equivalent to increasing base cell efficiency 28.3% → 30.1%



## **FUTURE WORK**

- Adapt fabrication procedure for CMO glass
  - MEAR effect is geometry based, similar AR expected
- Continue to investigate the effect of applying MEAR surface to rear of coverglass
- Design 1-U test panel to fly as hosted payload
- Investigate applications to micro-rovers



#### ACKNOWLEDGEMENTS



Research assistant & microfabrication trainee
 Juan Guzman



#### **SUPPLEMENTAL: MEAR THEORY**



$$\theta_m = \arcsin\left(m\frac{\lambda}{n\Lambda} - \sin(\theta_i)\right)$$



#### **SUPPLEMENTAL: MEAR THEORY**



$$\theta_m = \arcsin\left(m\frac{\lambda}{n\Lambda} - \sin(\theta_i)\right)$$



#### **SUPPLEMENTAL: MEAR THEORY**



# **SUPPLEMENTAL: MOTH EYE DESIGN**

![](_page_31_Figure_1.jpeg)

- Height is most "free" parameter
- Pitch is limited by subwavelength condition

![](_page_31_Picture_4.jpeg)

# **SUPPLEMENTAL: MOTH EYE DESIGN**

![](_page_32_Figure_1.jpeg)

- Height is most "free" parameter
- Pitch is limited by subwavelength condition

![](_page_32_Picture_4.jpeg)

# **SUPPLEMENTAL: MOTH EYE DESIGN**

![](_page_33_Figure_1.jpeg)

- Height is most "free" parameter
- · Pitch is limited by subwavelength condition

![](_page_33_Picture_4.jpeg)

## **SUPPLMENTAL: SIZE REDUCTION**

![](_page_34_Picture_1.jpeg)

O<sub>2</sub> etch yields etch rate of ~60nm/min.

![](_page_34_Picture_3.jpeg)

![](_page_34_Picture_4.jpeg)

## **SUPPLMENTAL: ETCH RATE**

![](_page_35_Figure_1.jpeg)

![](_page_35_Picture_2.jpeg)

## **SUPPLEMENTAL: MEASUREMENT RATIONALE**

![](_page_36_Figure_1.jpeg)

![](_page_36_Picture_2.jpeg)

## **SUPPLEMENTAL: BEAM CHARACTERIZATION**

![](_page_37_Figure_1.jpeg)

![](_page_37_Picture_2.jpeg)

# **SUPPLEMENTAL: BEAM CHARACTERIZATION**

![](_page_38_Figure_1.jpeg)

- Beam profile smooth.
  - Appears as an extended Airy disk.
  - Cells are not positioned below 3mm mark.

![](_page_38_Picture_5.jpeg)

![](_page_38_Picture_6.jpeg)

# **SUPPLEMENTAL: TEMPERATURE**

![](_page_39_Figure_1.jpeg)

- Very low temperature response in  $I_{SC}, V_{OC}$  a different matter.
- Relative measurements → identical electrical heating

![](_page_39_Picture_4.jpeg)

# **SUPPLEMENTAL: DRIFT**

![](_page_40_Figure_1.jpeg)

- Beam drift immediately following ignition
- May be accounted for by linear relationship with photodiode

![](_page_40_Picture_4.jpeg)

## **SUPPLEMENTAL: RC-LAG**

![](_page_41_Figure_1.jpeg)

- RC-Lag in the circuit
- 5% of final value
- First 0.5s of signal following crossover

![](_page_41_Picture_5.jpeg)

#### **SUPPLEMENTAL: RC-LAG**

![](_page_42_Figure_1.jpeg)

• RC-component not significant.

![](_page_42_Picture_3.jpeg)

# **SUPPLEMENTAL: EXPECTED UNCERTAINTIES**

Parameter	Symbol	Value (3σ)	Value as %
I <sub>SC</sub> readout	σl <sub>sc</sub>	0.00432 (mA)	< 0.385
Power sensor	$\sigma B_{\lambda}$		0.161
Position of cell on PCB (at 0°)	σX <sub>R</sub>	0.1mm	0.484
Horizontal position of PCB (at 0°)	σX <sub>0</sub>	0.1mm	0.489
Vertical position of PCB (at 0°)	σY <sub>0</sub>	0.1mm	0.006
Incident angle (at 0°)	σθο	1.25 arcmin	0.00002
Position of cell on PCB (at 85°)	σX <sub>R</sub>	0.1mm	0.004
Horizontal position of PCB (at 85°)	σX <sub>0</sub>	0.1mm	0.036
Vertical position of PCB (at 85°)	σY <sub>0</sub>	0.1mm	0.006
Incident angle (at 85°)	σθο	1.25 arcmin	0.832
Total uncertainty in relative Transmission (T <sub>1</sub> /T <sub>2</sub> )	σ <sub>T</sub>	< 0.021	

![](_page_43_Picture_2.jpeg)